

ABSTRACT

The invention relates to a high frequency  
circuit module in which a two- or more-layer dielectric  
substrate is used, the dielectric substrate between a  
5 conductor line of a matching circuit on the input side  
or on the output side and ground metal is composed of  
two or more layers and the miniaturization is enabled  
and a communication device using it.

As a required part can be thickened without  
10 changing the thickness of the whole dielectric  
substrate, the transmission loss can be reduced and the  
miniaturization of the high frequency circuit module  
and the communication device using it is enabled.